

InvenSense ITG-3200 – 3-Axis Gyroscope

Reverse Costing Analysis

by System Plus Consulting

Physical Analysis of the Device

Step by Step Reconstruction of the Process Flow

Cost of Manufacturing and Estimation of Selling Price

System Plus Consulting is proud to publish the reverse costing report of the 3-Axis MEMS Gyroscope ITG-3200 supplied by InvenSense.

The ITG-3200 is the first 3-axis (Pitch-Roll-Yaw) gyro developed by InvenSense. It uses a very thin 4x4x0.9mm QFN package. The components are manufactured on 200mm wafers using a three-bonded-wafer process: a thin sensor wafer and a protective cap wafer both processed by Deep RIE, and an ASIC wafer for signal conditioning.

The ITG-3200 3-Axis gyroscopes are suitable for various motion processing solutions for consumer products.

This report provides complete teardown of the MEMS Gyroscope with:

- Detailed photos
- Material analysis
- Schematic assembly description
- Manufacturing Process Flow
- In-depth economical analysis
- Manufacturing cost breakdown
- Selling price estimation

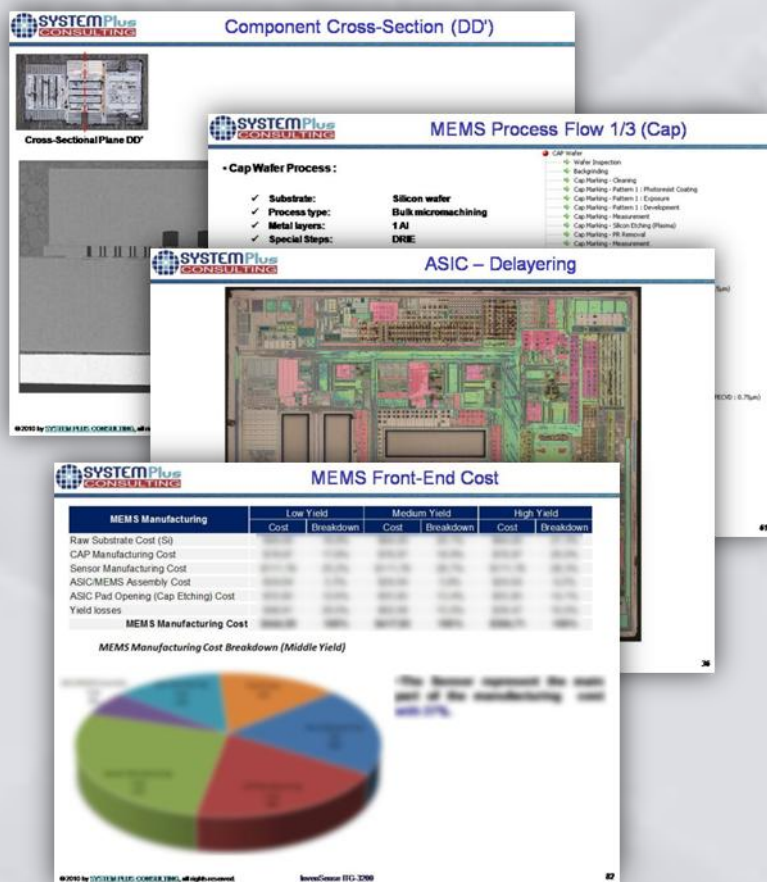


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